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High Temperature Touch Through Glass

Project Title: Designed for: Public Release

Assembly Variant: 001

PCB Number: TIDA-00464
PCB Rev: E1

Label Table

<table>
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<tr>
<th>Variant</th>
<th>Label Text</th>
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<td>001</td>
<td>ChangeMe!</td>
</tr>
<tr>
<td>002</td>
<td>ChangeMe!</td>
</tr>
</tbody>
</table>

Assembly Note

ZZ1

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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